



Material Content Data Sheet



Sales Product Name		BSD235C H6327		Issued		19. July 2018		
MA#		MA001231716						
Package		PG-SOT363-6-1		Weight*		6.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.04		394	
	noble metal	gold	7440-57-5	0.010	0.15		1529	
	inorganic material	silicon	7440-21-3	0.128	2.03	2.22	20327	22250
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1374	
	non noble metal	copper	7440-50-8	2.869	45.59	45.79	455919	457843
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1644	1644
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4754	
	plastics	epoxy resin	-	0.643	10.22		102221	
	inorganic material	silicondioxide	60676-86-0	2.319	36.85	47.55	368473	475448
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33883	33883
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8932	8932
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com